APPLICA	BLE STAN	DARD									
RATING	OPERATING		1 0000 TO 0500 (NOTE 1)		STORAGE TEMPERATU	IRE RANGE	-10°C TO 60	°C (NOTE	2)		
Willio	TEMPERATURE RANGE OPERATING				STORAGE			-	<u> </u>		
	HUMIDITY RANGE VOLTAGE		40% TO 80% AC 250V		HUMIDITY R	VOLTAGE		40% TO 70% (NOTE 2) AC 30V			
	VOLITICE				UL·CSA	VOLIAGE	AWG 22		· ·		
	CURRENT		1		RATING			: 1/			
							AWG 30 : 0.5				
			SPEC	IFICA	TIONS						
IT	 ГЕМ		TEST METHOD			REG	QUIREMENTS		QT	A	
CONSTR	RUCTION	l			I						
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.			ACCO	ACCORDING TO DRAWING.				Х	
MARKING		CONFIRMED VISUALLY.							Χ	X	
	IC CHARA										
		100 mA (DC OR 1000 Hz).				30 mΩ MAX.			Х	_	
INSULATION RESISTANCE						1000 MΩ MIN.			X	-	
			650 V AC FOR 1 min.			NO FLASHOVER OR BREAKDOWN.				_	
	VICAL CHA										
MECHANICAL OPERATION 3		I 30 TIME	30 TIMES INSERTIONS AND EXTRACTIONS.			① CONTACT RESISTANCE: 30mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			Х	_	
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			-	 NO ELECTRICAL DISCONTINUITY OF 1μs. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			Х	_	
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			ES PAF				Х		
FNVIROI	NMFNTAL		ACTERISTICS								
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 \rightarrow 5 TO 35 \rightarrow +85 \rightarrow 5 TO 35 $^{\circ}$ C TIME 30 \rightarrow 5 TO 15 \rightarrow 30 \rightarrow 5 TO15 min UNDER 5 CYCLES.			min 2 INSI 3 NO	 CONTACT RESISTANCE: 30mΩ MAX. INSULATION RESISTANCE: 1000MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			Х	_	
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			2 INSI 3 NO	CONTACT RESISTANCE: 30mΩ MAX. INSULATION RESISTANCE: 500MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			Χ	_	
RESISTANCE TO SOLDERING HEAT		1) AUTOMATIC SOLDERING (REFLOW) 《REFLOW AREA》 MAX 240°C WITHIN 10 sec. MIN 220°C WITHIN 30sec. 《PREHEATING AREA》 150°C 100 TO 120 sec. PUT THROUGH IN REFROW FURNACE TWICE. FEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNEVCTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :290±10°C, SOLDERING TIME :3s. NO STRENGTH ON CONTACT. SOLDERED AT SOLDER TEMPERATURE, 230±5°C FOR IN IMMERSION, DURATION, 3 s.			A NEW COVER	A NEW UNIFORM COATING OF SOLDER SHALL COVER MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.				_	
COUN	IT D	ESCRIPTION	ON OF REVISIONS		DESIGNED		CHECKED		DA	TE	
<u> </u>				SE BY CURRENT.			APPROVED TS. SAKATA			08. 12. 16	
REMARKS NOTE 1:INCLU	DING THE TEMP	ERATURE R	ISE BY CURRENT.			I CHECKE	D I TS KUMAZAWA			2. 1	
NOTE 1:INCLU NOTE 2:APPLY	TO THE CONDI	TION OF LOI	NG TERM STORAGE FOR UNUS							_	
IOTE 1:INCLU IOTE 2:APPLY BEFOI HUMIE	/ TO THE CONDI [*] RE PCB ON BOA DITY RANGE IS A	ΓΙΟΝ OF LOI RD , AFTER PPLIED FOF	NG TERM STORAGE FOR UNUS PCB BOARD , OPERATING TEMF R INTERM STORAGE DURING TR	PERATURE A	AND	DESIGNE	D KT. ISHII	(08. 12		
IOTE 1:INCLU NOTE 2:APPLY BEFOI HUMIE Unless otherw	/ TO THE CONDI' RE PCB ON BOA DITY RANGE IS A vise specifid , ref	FION OF LOI RD , AFTER PPLIED FOF er to JIS C	NG TERM STORAGE FOR UNUS PCB BOARD , OPERATING TEMI R INTERM STORAGE DURING TR 5402.	PERATURE A	AND TION.	DESIGNE DRAWN	D KT. ISHII KT. ISHII	(08. 1 <i>2</i> 08. 1 <i>2</i>		
NOTE 1:INCLU NOTE 2:APPLY BEFOI HUMIE Jnless otherw Note QT:QI	TO THE CONDITED TO THE PCB ON BOADITY RANGE IS A vise specifid, refulalification Tes	FION OF LOT RD, AFTER PPLIED FOF er to JIS C	NG TERM STORAGE FOR UNUS PCB BOARD , OPERATING TEMF R INTERM STORAGE DURING TR 5402. urance Test X:Applicable Te	PERATURE A	DRAWIN	DESIGNE DRAWN	KT. ISHII KT. ISHII ELC4-16	62226-	08. 1 <i>2</i> 08. 1 <i>2</i>		
NOTE 1:INCLU NOTE 2:APPLY BEFOI HUMIE Unless otherw	TO THE CONDITED TO THE PCB ON BOADITY RANGE IS A vise specifid, refulalification Tes	FION OF LOT RD, AFTER PPLIED FOF er to JIS C	NG TERM STORAGE FOR UNUS PCB BOARD , OPERATING TEMI R INTERM STORAGE DURING TR 5402.	PERATURE A	AND TION.	DESIGNE DRAWN	D KT. ISHII KT. ISHII	62226-	08. 1 <i>2</i> 08. 1 <i>2</i>		